

#### **DATA SHEET**

# SKY13551-668LF: 0.4 to 3.8 GHz DP10T (SP5T/SP5T) Main/Receive Diversity Switch with MIPI RFFE Interface for Carrier Aggregation

# **Applications**

- 3G/4G multimode cellular handsets (UMTS, CDMA2000, LTE)
- Carrier aggregation diversity

#### **Features**

- Broadband frequency range: 0.4 to 3.8 GHz
- Single, positive DC power supply (2.5 to 4.8 V)
- Integrated, programmable MIPI interface using separate registers for ANT\_A and ANT\_B
- Dual antenna ports can be connected externally to a diplexer
- Small QFN (16-pin, 1.6 x 2.4 x 0.55 mm) package (MSL1, 260 °C per JEDEC J-STD-020)





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## **Description**

The SKY13551-668LF is a dual single-pole, five-throw (2xSP5T) Mobile Industry Processor Interface (MIPI) controlled antenna switch designed specifically for receive diversity in carrier aggregation applications.

The 2xSP5T switch is optimized for broadband performance. Using advanced switching technologies, the SKY13551-668LF maintains low insertion loss and high isolation for all switching paths. The high-linearity performance and low insertion loss achieved by the SKY13551-668LF makes it an ideal choice for carrier aggregation applications in both main and diversity antenna switching. The switch also exhibits excellent second/third order intermodulation distortion (IMD2/IMD3) performance.

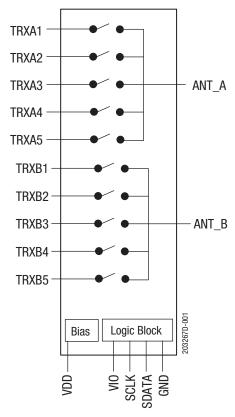


Figure 1. SKY13551-668LF Block Diagram

Switching is controlled by an integrated MIPI decoder. The two switches can be configured independently. There are separate registers for each SP5T switch. No external DC blocking capacitors are required on the RF paths as long as no DC voltage is applied to those paths.

The SKY13551-668LF is manufactured in a compact, 1.6 x 2.4 x 0.55 mm, 16-pin surface-mount Quad Flat No-Lead (QFN) package.

A functional block diagram is shown in Figure 1. The pin configuration and package are shown in Figure 2. Signal pin assignments and functional pin descriptions are provided in Table 1.

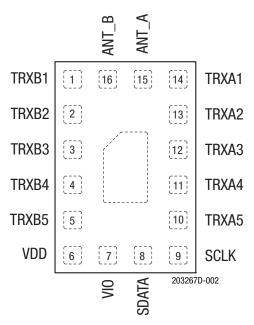


Figure 2. SKY13551-668LF Pinout (Top View)

Table 1. SKY13551-668LF Signal Descriptions<sup>1</sup>

Pin	Name	Description	Pin	Name	Description
1	TRXB1	Ant B transmit/receive port 1	9	SCLK	Clock
2	TRXB2	Ant B transmit/receive port 2	10	TRXA5	Ant A transmit/receive port 5
3	TRXB3	Ant B transmit/receive port 3	11	TRXA4	Ant A transmit/receive port 4
4	TRXB4	Ant B transmit/receive port 4	12	TRXA3	Ant A transmit/receive port 3
5	TRXB5	Ant B transmit/receive port 5	13	TRXA2	Ant A transmit/receive port 2
6	VDD	DC power supply	14	TRXA1	Ant A transmit/receive port 1
7	VIO	MIPI interface DC supply voltage	15	ANT_A	Ant A port
8	SDATA	Data	16	ANT_B	Ant B port

<sup>1</sup> Bottom ground paddles must be connected to ground.

## **Electrical and Mechanical Specifications**

The absolute maximum ratings of the SKY13551-668LF are provided in Table 2. Electrical specifications are provided in Tables 3 and 4.

IMD2 and IMD3 test conditions for various frequencies are listed in Tables 5 and 6, respectively.

Figure 3 illustrates the test setup used to measure intermodulation products. This industry standardized test is used to simulate the WCDMA linearity of the antenna switch. A +20 dBm continuous wave (CW) signal, ffund, is sequentially applied to the TRX ports, while a -15 dBm CW blocker signal, fblk, is applied to the ANT port.

The resulting third order intermodulation distortion (IMD3), frx, is measured over all phases of frund. The SKY13551-668LF exhibits exceptional performance for all RF ports.

Table 7 describes the register content and programming read/write sequences. Refer to the *MIPI Alliance Specification for RF Front-End Control Interface (RFFE)*, v1.10 (26 July 2011) for additional information on MIPI programming sequences and MIPI bus specifications.

Figure 4 provides the timing diagram for register write commands. Figure 5 provides the timing diagram for register read commands.

Register descriptions and programming information is provided in Table 8. Tables 9 and 10 provide the Register\_0 and Register\_1 logic, respectively.

Table 2. SKY13551-668LF Absolute Maximum Ratings<sup>1</sup>

Parameter	Symbol	Minimum	Maximum	Units
Supply voltage	VDD	2.5	5.0	V
Digital control signal	Vio		2	V
SCLK port voltage	Vsclk		Vio	V
SDATA port voltage	VSDATA		Vio	V
LTE input power	Pin		+31	dBm
Storage temperature	Тѕтс	-55	+150	°C
Operating temperature	Тор	-30	+90	°C

<sup>1</sup> Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

**CAUTION**: Although this device is designed to be as robust as possible, electrostatic discharge (ESD) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions should be used at all times.

Table 3. SKY13551-668LF RF Electrical Specifications  $^1$  (1 of 2) (VDD = 2.85 V, TOP = +25 °C, Characteristic Impedance [Zo] = 50  $\Omega$ , Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typical	Max	Units
Operating frequency	f		0.4		3.8	GHz
Insertion loss	IL	ANT_A to any TRxA port ANT_B to any TRxB port:				
		400 to 824 MHz 824 to 960 MHz 1427 to 1511 MHz 1710 to 2170 MHz 2170 to 2690 MHz 3400 to 3800 MHz		0.40 0.45 0.5 0.80 1.0 1.3	0.60 0.60 0.7 1.0 1.2 1.6	dB dB dB dB dB
Isolation	ISO	ANT_A or ANT_B to any "off" TRx port:				
		Up to 787 MHz Up to 960 MHz Up to 1511 MHz Up to 1990 MHz Up to 1990 MHz Up to 2170 MHz Up to 2690 MHz Up to 3800 MHz	31 30 24 22 21 18 15	34 33 29 25 24 21 18		dB dB dB dB dB dB
		ANT_A to any TRxB port ANT_B to any TRxA port:				
		Up to 787 MHz Up to 960 MHz Up to 1511 MHz Up to 1990 MHz Up to 2170 MHz Up to 2690 MHz Up to 3800 MHz	40 38 34 32 31 29 26	42 40 37 33 32 30 27		dB dB dB dB dB dB
		ANT_A to ANT_B:				
		400 to 960 MHz 1427 to 1511 Mhz 1710 to 1990 MHz 1980 to 2690 MHz 3400 to 3800 MHz	31 26 25 22 18	32 28 26 23 19		dB dB dB dB dB
"On" state match	VSWR	400 to 2170 MHz		1.6:1	2:1	
Second order intermodulation distortion	IMD2	See Table 5		-105	-100	dBm
Third order intermodulation distortion	IMD3	See Table 6		-105	-100	dBm
Low-band 2 <sup>nd</sup> and 3 <sup>rd</sup> harmonic	2fo, 3fo	Any TRx port, PIN = +26 dBm, f = 900 MHz		-70	-64	dBm
		Any TRx port, $PIN = +26$ dBm, $f0 = 900$ MHz, $VSWR = 5:1$		-65	-60	dBm
Middle-band 2 <sup>nd</sup> and 3 <sup>rd</sup> harmonics	2fo, 3fo	Any TRxA and any TRxB port, $PIN = +26$ dBm, $f1 = 1462$ MHz, $f2 = 1910$ MHz		-70	-65	dBm
		Any TRxA and any TRxB port, $PIN = +26$ dBm, f1 = 1462 MHz, f2 = 1910 MHz, $VSWR = 5:1$		-65	-58	dBm
High-band 2 <sup>nd</sup> and 3 <sup>rd</sup> harmonic	2fo, 3fo	Any TRxA and any TRxB port, PIN = +26 dBm, f0 = 2690 MHz		-61	<b>–</b> 55	dBm
		Any TRxA and any TRxB port, PIN = +26 dBm, $f0 = 2690$ MHz, $VSWR = 5:1$		-59	-53	dBm

Table 3. SKY13551-668LF RF Electrical Specifications (2 of 2) (VDD = 2.85 V, TOP = +25 °C, Characteristic Impedance [Zo] = 50  $\Omega$ , Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typical	Max	Units
Band 13 2 <sup>nd</sup> harmonic	2fo	Any TRx port, $PIN = +25 \text{ dBm}$ , $f0 = 782 \text{ MHz}$		-77		dBm
Band 17 3 <sup>rd</sup> harmonic	3fo	Any TRx port, PIN = +25 dBm, f = 707 MHz		-77		dBm
Turn-on time	ton	From application of VDD and VIo or transition from low power mode			20	μs
Wake-up time	tw	From isolation state		2	5	μs
Switching speed	tsw	Any state to any other state		2	5	μs

<sup>&</sup>lt;sup>1</sup> Performance is guaranteed only under the conditions listed in this table.

Table 4. SKY13551-668LF DC Electrical Specifications<sup>1</sup> (V<sub>DD</sub> = 2.85 V, V<sub>IO</sub> = 1.8 V, T<sub>OP</sub> = +25 °C, Characteristic Impedance [Z<sub>O</sub>] = 50  $\Omega$ , Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typical	Max	Units
Supply voltage	VDD		2.50	2.85	4.8	٧
Supply current, active mode	IDD			35	100	μА
Interface supply voltage level	Vio		1.65	1.80	1.95	V
Digital data and clock signals: High Low	VSDATA, VSCLK		0.8 × Vi0 0		VI0 0.2 × VI0	V V
Interface supply current	lvio			5	50	μΑ

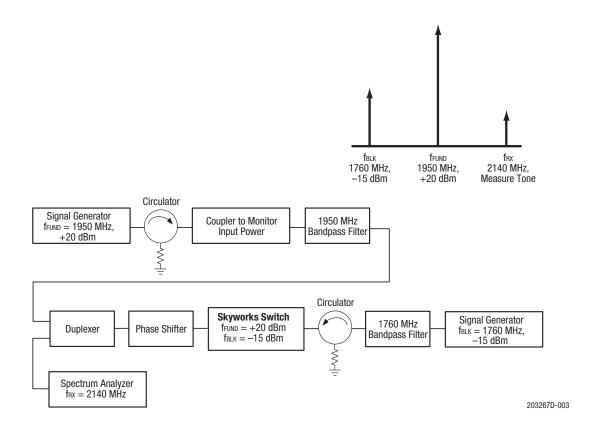
<sup>&</sup>lt;sup>1</sup> Performance is guaranteed only under the conditions listed in this table.

### **Table 5. IMD2 Test Conditions**

Band	Transmit Frequency (MHz)	Transmit Power (dBm)	Frequency Blocker, Low (MHz)	Frequency Blocker, High (MHz)	Power Blocker (dBm)	Receive Frequency (MHz)
1	1950		190	4090		2140
2	1880		80	3840		1960
4	1732		400	3864		2132
5	836.5	+20	45	1718	<b>–15</b>	881.5
7	2535		120	5187		2655
8	897		45	1839		942
11/21	1452			2952		1500

## **Table 6. IMD3 Test Conditions**

Band	Transmit Frequency (MHz)	Transmit Power (dBm)	Frequency Blocker (MHz)	Power Blocker (dBm)	Receive Frequency (MHz)
1	1950		1760		2140
2	1880		1800		1960
4	1732		1332		2132
5	836.5	+20	791.5	<b>–1</b> 5	881.5
7	2535		2415		2655
8	897		852		942
11/21	1452		1404		1500



**Figure 3. Typical Third Order Intermodulation Test Setup** 

**Table 7. Command Sequence Bit Definitions** 

									Extended Operation					
Туре	SSC	C11-C8	<b>C7</b>	C6-C5	C4	C3-C0	Parity Bits	BPC	DA7(1)- DA0(1)	Parity Bits	BPC	DA7(n)- DA0(n)	Parity Bits	BPC
Reg_0 Write, Short Command	Υ	SA[3:0]	1b	Data[6:5]	Data[4]	Data{3:0]	Y	Y	-	-	-	-	-	-
Reg_0 Write, Long Command	Y	SA[3:0]	0	10b	Addr[4]	Addr[3:0]	Y	-	Data[7:0]	-	-	-	Υ	Y
Reg_1 Write	Υ	SA[3:0]	0	10b	Addr[4]	Addr[3:0]	Y	-	Data[7:0]	-	-	-	Υ	Y
Reg Read	Υ	SA[3:0]	0	11b	Addr[4]	Addr[3:0]	Y	Y	Data[7:0]	-	_	_	Υ	Υ

#### Legend:

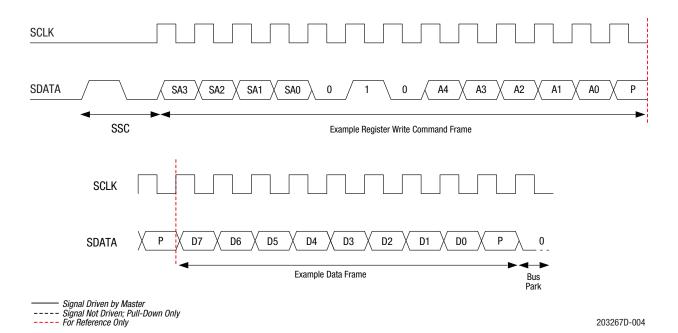
SSC = Sequence start command

DA = Data/address frame bits

BC = Byte count (# of consecutive addresses)

C = Command frame bits

BPC = Bus park cycle



**Figure 4. Register Write Command Timing Diagram** 

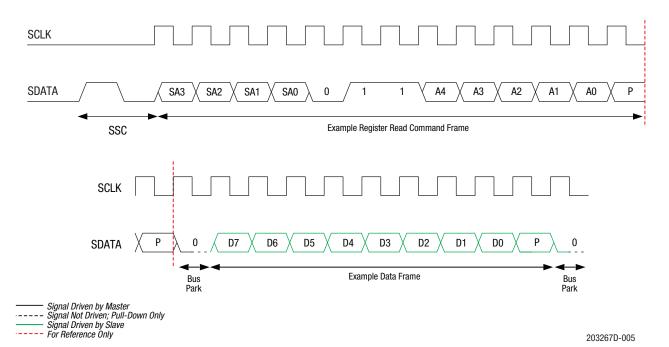


Figure 5. Register Read Command Timing Diagram

**Table 8. Register Description and Programming** 

Register					
Name	Address (Hex)	Parameter	Description	Default (Binary)	
Register_0	0000	MODE_CTRL	Bits[6:0]:	0000000	
			See Table 10 for logic		
Register_1	0001	MODE_CTRL	Bits[7:0]:	00000000	
			See Table 11 for logic		
		PWR_MODE	Bits[7:6]:	00	
			00 = Normal operation (active) 01 = Default settings (startup) 10 = Low power (low power) 11 = Reserved		
		Trigger_Mask_2	Bit[5]:	0	
			If this bit is set, trigger 2 is disabled. When all triggers are disabled, if writing to a register that is associated with trigger 2, the data goes directly to the destination register.		
		Trigger_Mask_1	Bit[4]:	0	
PM_TRIG (Note 1)	001C		If this bit is set, trigger 1 is disabled. When all triggers are disabled, if writing to a register that is associated with trigger 1, the data goes directly to the destination register.		
		Trigger_Mask_0	Bit[3]:	0	
			If this bit is set, trigger 0 is disabled. When all triggers are disabled, if writing to a register that is associated with trigger 0, the data goes directly to the destination register.		
		Trigger_2	Bit[2]:	0	
			If this bit is set, data is loaded into the trigger 2 registers.		
		Trigger_1	Bit[1]:	0	
			If this bit is set, data is loaded into the trigger 1 registers.		
		Trigger_0	Bit[0]:	0	
			If this bit is set, data is loaded into the trigger 0 registers.		
PRODUCT_ID	001D	PRODUCT_ID	Bits[7:0]:	11010110	
			This is a read-only register. However, during the programming of the Unique Slave Identifier (USID), a write command sequence is performed on this register but the value is not changed.		
MANUFACTURER_ID	001E	MANUFACTURER_ID	Bits[7:0]:	10100101	
			Read-only register		
		Reserved	Bits[7:6]:	00	
			Reserved		
MAN_USID	001F	MANUFACTURER_ID	Bits[5:4]:	01	
INIWIATO OPID	UUIF		Read-only register		
		USID	Bits[3:0]:	1010	
			Programmable USID. A write to these bits programs the USID.		

<sup>1</sup> Unlike the complete independence between triggers 0, 1, and 2, and also between the associated trigger masks 0, 1, and 2, respectively, as described in the MIPI RFFE Specification, this device uses additional interactions between the provided trigger functions.

The delayed application of updated data to all triggerable registers in this device may be accomplished using any of the three triggers (0, 1, or 2), provided that the particular trigger used is not currently masked off. If multiple triggers are enabled, any or all of those are sufficient to cause the data to be transferred from shadow registers to destination registers for all triggerable registers in the device.

It is also necessary to disable all three triggers (i.e., set all three trigger masks) to ensure that data written to any triggerable register will immediately be written to the destination register at the conclusion of the RFFE command sequence where the data is written.

Table 9. Register\_0 Truth Table (Ant B)

		Register 0 Bits										
On State	D7	D6	D5	D4	D3	D2	D1	D0				
All isolation				0	0	0	0	0				
TRxB1				0	0	0	0	1				
TRxB2				0	0	0	1	0				
TRxB3				0	0	0	1	1				
TRxB4				0	0	1	0	0				
TRxB5				0	0	1	0	1				
Isolation				0	0	1	1	0				
TRxB5				0	0	1	1	1				
TRxB4				0	1	0	0	0				
TRxB3				0	1	0	0	1				
TRxB2				0	1	0	1	0				
TRxB1				0	1	0	1	1				
TRxB5+4				0	1	1	0	0				
TRxB5+3				0	1	1	0	1				
TRxB5+2				0	1	1	1	0				
TRxB5+1				0	1	1	1	1				
TRxB4+3				1	0	0	0	0				
TRxB4+2				1	0	0	0	1				
TRxB4+1				1	0	0	1	0				
TRxB3+2				1	0	0	1	1				
TRxB3+1				1	0	1	0	0				
TRxB2+1				1	0	1	0	1				
All isolation				1	0	1	1	0				
All isolation				1	0	1	1	1				
All isolation				1	1	0	0	0				
All isolation				1	1	0	0	1				
All isolation				1	1	0	1	0				
All isolation				1	1	0	1	1				
All isolation				1	1	1	0	0				
All isolation				1	1	1	0	1				
All isolation				1	1	1	1	0				
All isolation				1	1	1	1	1				

Table 10. Register\_1 Truth Table (Band A)

		Register 0 Bits									
On State	D7	D6	D5	D4	D3	D2	D1	D0			
All isolation				0	0	0	0	0			
TRxA1				0	0	0	0	1			
TRxA2				0	0	0	1	0			
TRxA3				0	0	0	1	1			
TRxA4				0	0	1	0	0			
TRxA5				0	0	1	0	1			
Isolation				0	0	1	1	0			
TRxA5				0	0	1	1	1			
TRxA4				0	1	0	0	0			
TRxA3				0	1	0	0	1			
TRxA2				0	1	0	1	0			
TRxA1				0	1	0	1	1			
TRxA5+4				0	1	1	0	0			
TRxA5+3				0	1	1	0	1			
TRxA5+2				0	1	1	1	0			
TRxA5+1				0	1	1	1	1			
TRxA4+3				1	0	0	0	0			
TRxA4+2				1	0	0	0	1			
TRxA4+1				1	0	0	1	0			
TRxA3+2				1	0	0	1	1			
TRxA3+1				1	0	1	0	0			
TRxA2+1				1	0	1	0	1			
All isolation				1	0	1	1	0			
All isolation				1	0	1	1	1			
All isolation				1	1	0	0	0			
All isolation				1	1	0	0	1			
All isolation				1	1	0	1	0			
All isolation				1	1	0	1	1			
All isolation				1	1	1	0	0			
All isolation				1	1	1	0	1			
All isolation				1	1	1	1	0			
All isolation				1	1	1	1	1			

## **Evaluation Board Description**

The SKY13551-668LF Evaluation Board is used to test the performance of the SKY13551-668LF DP10T Switch. An Evaluation Board schematic diagram is provided in Figure 6. A recommended ESD protection circuit diagram is provided in Figure 7. An assembly drawing for the Evaluation Board is shown in Figure 8.

# **Package Dimensions**

The PCB layout footprint for the SKY13551-668LF is provided in Figure 9. Typical part markings are shown in Figure 10. Package dimensions are shown in Figure 11, and tape and reel dimensions are provided in Figure 12.

# **Package and Handling Information**

Instructions on the shipping container label regarding exposure to moisture after the container seal is broken must be followed. Otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY13551-668LF is rated to Moisture Sensitivity Level 1 (MSL1) at 260 °C. It can be used for lead or lead-free soldering. For additional information, refer to the Skyworks Application Note, *Solder Reflow Information*, document number 200164.

Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. Production quantities of this product are shipped in a standard tape and reel format.

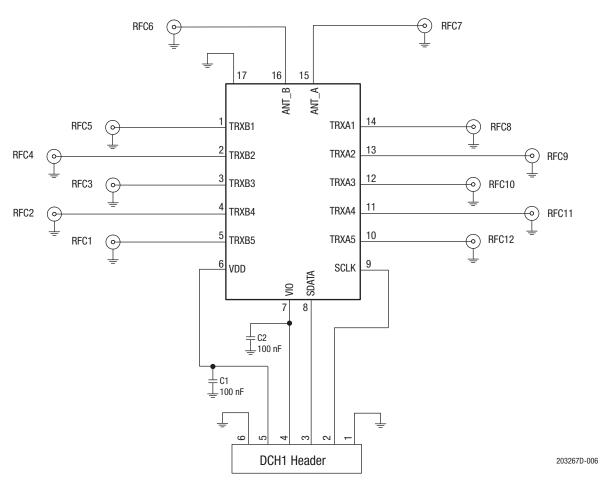


Figure 6. SKY13551-668LF Evaluation Board Schematic

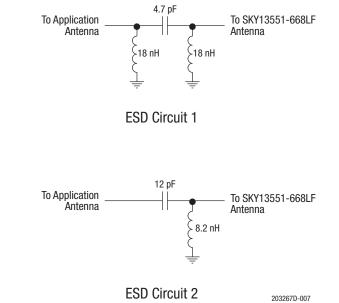


Figure 7. SKY13551-668LF Recommended ESD Protection Circuits

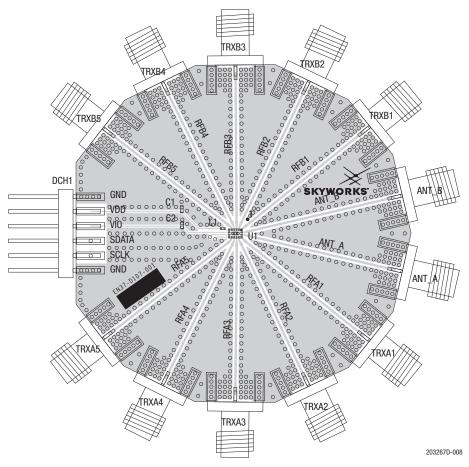
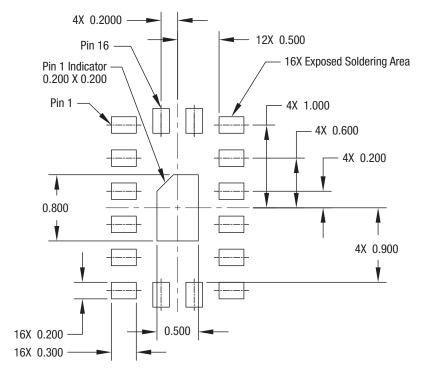


Figure 8. SKY13551-668LF Evaluation Board Assembly Diagram



All dimensions are in millimeters.

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Figure 9. SKY13551-668LF PCB Layout Footprint (Top View)

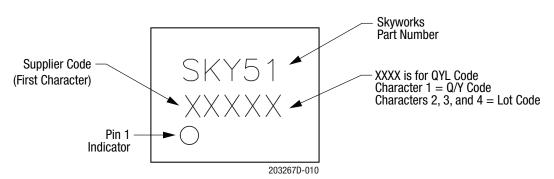


Figure 10. Typical Part Markings (Top View)

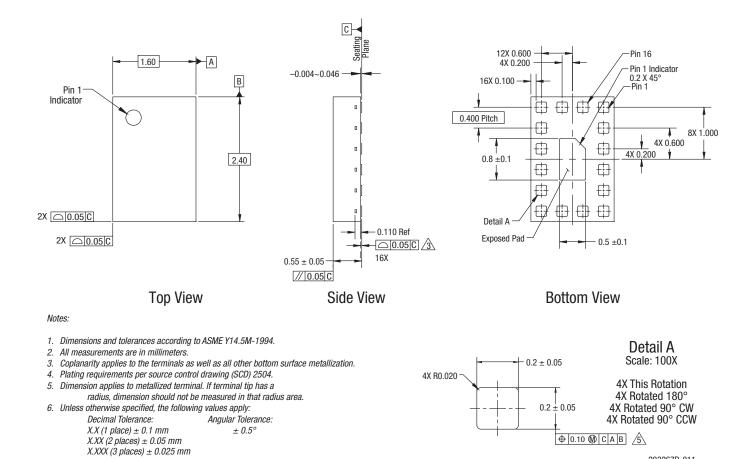
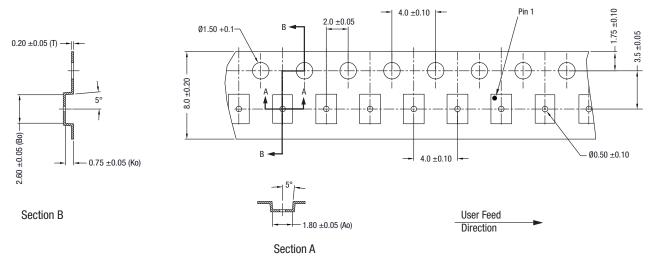


Figure 11. SKY13551-668LF Package Dimensions

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#### Notes:

- Carrier tape material: black conductive polystyrene or polycarbonate.
   Cover tape material: transparent conductive.
   ESD surface resistivity shall be ≤1 x 10¹⁰ Ohms/square per EIA, JEDEC TNR specification.
   10-sprocket hole pitch cumulative tolerance: ±0.20 mm.
- 5. Ao and Bo measured on plane 0.30 mm above the bottom of the pocket.
- 6. All dimensions are in millimeters.

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Figure 12. SKY13551-668LF Tape and Reel Dimensions